



# SOT371-1

plastic, shrink small outline package; 56 leads; 0.635 mm pitch; 18.45 mm x 7.5 mm x 2.8 mm body

30 January 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SSOP56
<b>Package type industry code</b>	SSOP56
<b>Package style descriptive code</b>	SSOP (shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-118
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-2-2003
<b>Manufacturer package code</b>	SOT371

Table 1. Package summary

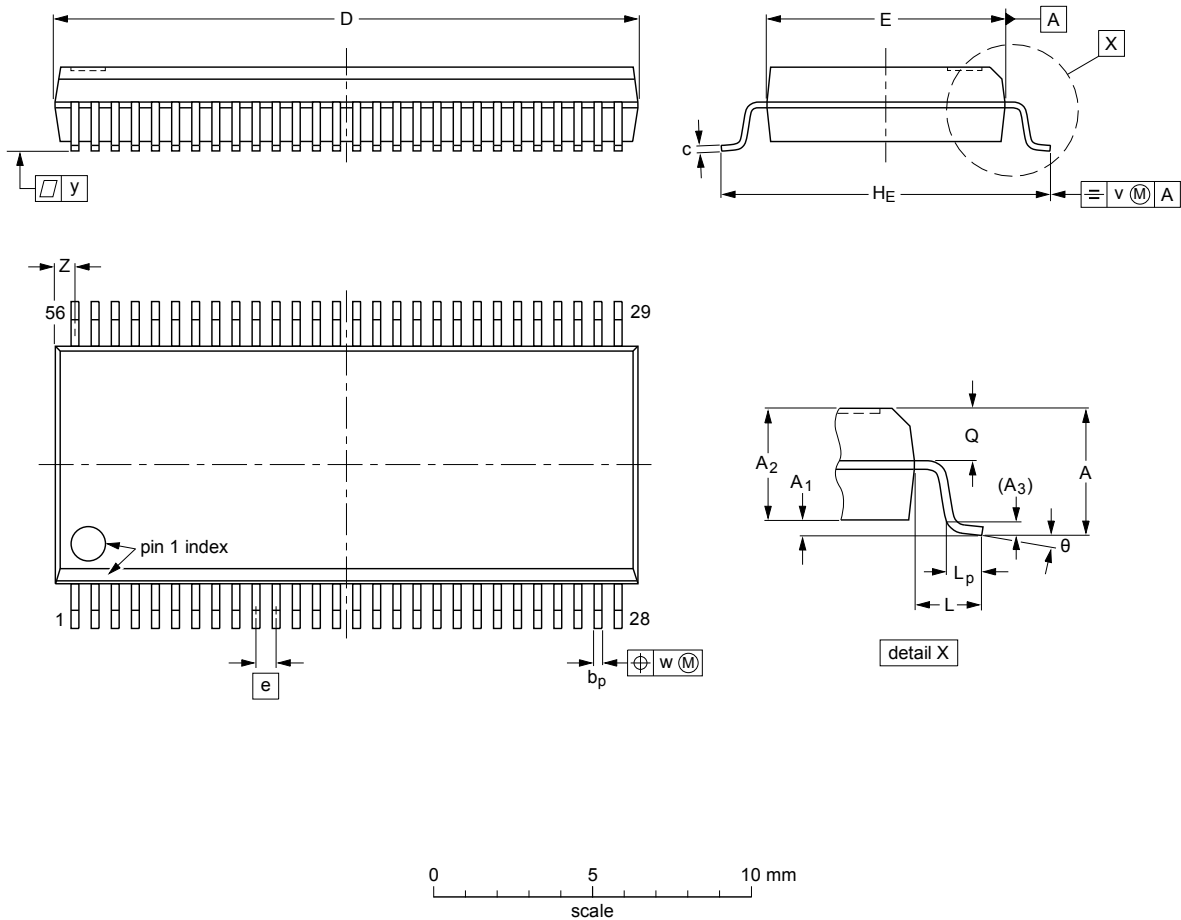
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	18.3	-	18.45	18.55	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	-	-	2.8	2.8	mm
A <sub>2</sub>	package height	2.2	-	2.3	2.35	mm
e	nominal pitch	-	-	0.635	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	56	-	

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## 2. Package outline

SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT371-1		MO-118				99-12-27 03-02-18

Fig. 1. Package outline SSOP56 (SOT371-1)

### 3. Soldering

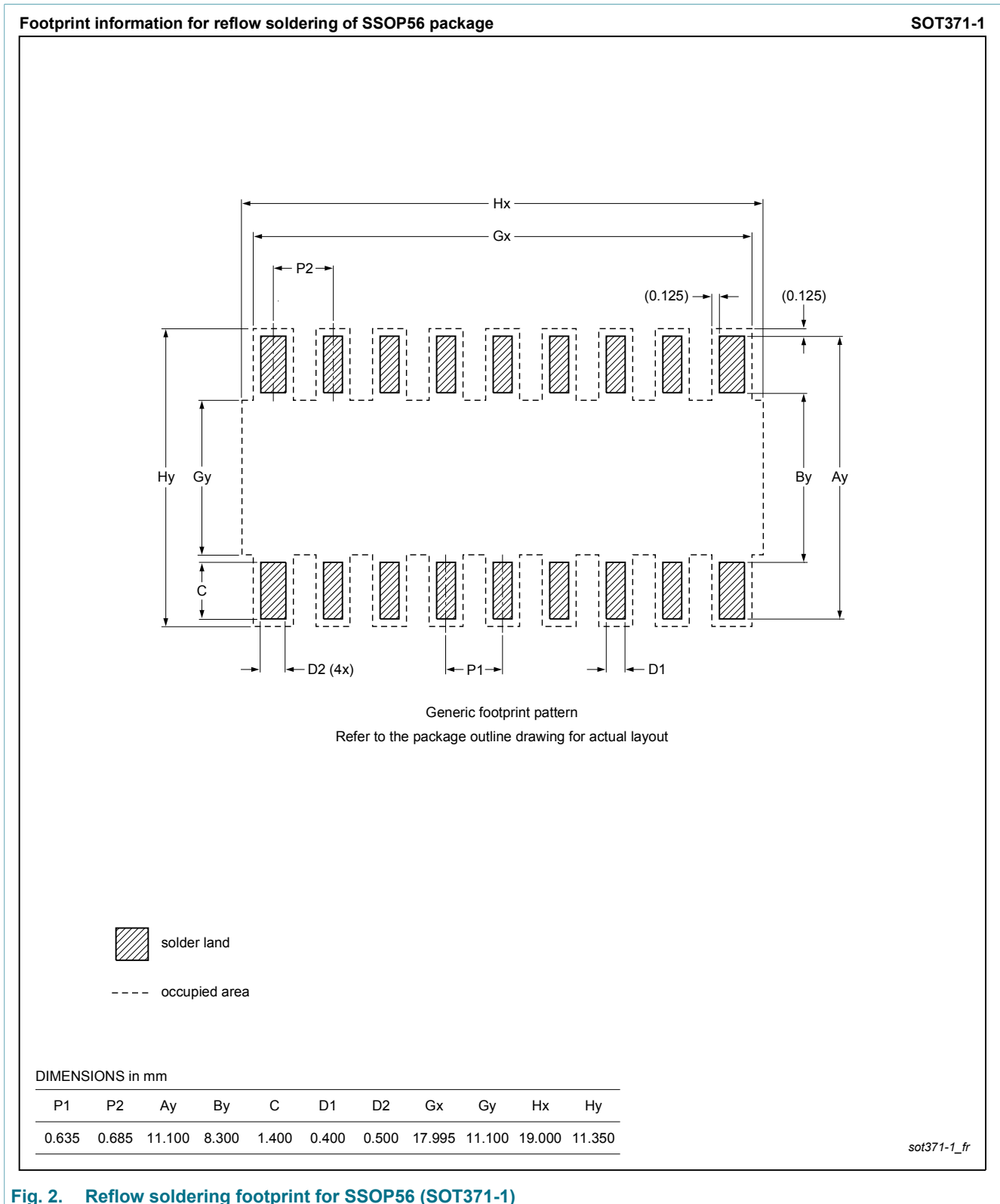


Fig. 2. Reflow soldering footprint for SSOP56 (SOT371-1)

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## 4. Legal information

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Date of release: 30 January 2017

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